Paste-Cat DS-0201HZ 5Sn2.5Ag92.5Pb

High Temp Solder Paste
DS-0201HZ 5Sn2.5Ag92.5Pb

Rev.00

Basic Materials

Alloy Application	Alloy(5Sn/2.5Ag/92.5Pb, 2Sn/2.5Ag/95.5Pb)
Powder Size	20~45㎛, 20~38 ㎛
Flux	Halide-free, Non-Toxic, No clean
Model No.	DS-0201FZ 5Sn2.5Ag92.5Pb, Printing Type

DESCRIPTION

DS-0201HZ 5Sn2.5Ag92.5Pb is a halide Zero and a no-clean type formulated for optimum performance in a wide variety of applications. The semi-soft, highly reliable residues provide a very low incidence of first probe false readings. Paste-Cat can be printed at high speed by squeegee and has a particular adhesiveness.

1. This is a as non-cleaning Solder Paste, The flux residue is just a little.
2. After reflow soldering, the residue is transparent and clean.
3. Suitable for high Speeds printing is and doesn't adhere to the squeeze.
4. Excellent wetting characteristics and good Printability for fine pitch.
5. Penetrable flux residues to maximize pin testability(ICT).
6. Paste-Cat exhibits long stencil and tack life > 8 hours (@23℃, 50%RH).

STORAGE AND USE

DS-0201HZ 5Sn2.5Ag92.5Pb is generally 500g packed individually and 10kg in inner box. When ship to oversea, 20Kg Master box is thermally controlled cool with several ice packs. If especially order, we could a separate wrap and should be stored refrigerated upon receipt at 1-10℃. Paste-Cat shall be aged to reach room temperature over 2~3 hours before using.
Prolonged storage at room temperature may deteriorate the quality of Solder paste
While the flux system is not considered toxic, its use in typical reflow will generate a small amount of reaction and decomposition vapors. These vapors should be adequately exhausted from the work area. Consult the MSDS for additional safety information.
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Danyang SOLTEC

29, 660Beongil Madoro Mado-myeon, Hwaseong-si, Kyunggi-Do, S-Korea
Tel: +82-31-355-9131, Fax:+82-31-355-9138, www.dyst21.co.kr

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PHYSICAL AND CHEMICAL PROPERTIES

Kind of Test		Printing Type	Remark
Alloy Application		5Sn/2.5Ag/92.5Pb	J-STD-005A
Liquidus Temp (℃)		296	
Powder Size (㎛), #3, #4		20~45, 20~38	J-STD-005A
Metal Content (w/w, %)		91.5±1.0	J-STD-005A
Flux Residue (%)		3.5~3.7	After soldering
Viscosity (Pa.s)		160±15	@ 25℃ (by PCU-205)
S.I.R (Ω)	Before	4.4×10^{13}	40°C, 95% RH
	After	3.8×10^{12}	96 Hours
Solder Ball Test		Good	IPC J-STD-005
Spread Test (%)		92%	IPC J-STD-005
Application Pitch (mm)		0.2~0.6	
Halogen Content (%)		Zero	IPC J-STD-004
Copper Corrosion		No Corrosion	IPC – TM -650
Dry Time (Stencil Life. Hr)		8	23°C, 50% RH
Shelf Life		3 Months	@ 1~10℃

Guide line for soldering

- Stencil : Laser Cut Application
- Squeegee : Recommend Metal
- Conveyer Speed : 25mm ~ 200mm/sec
- Temp. Profile : Ramp @ 25 ~ 150 ℃ / min to 145 ~ 160℃
  Dwell @ 165 ~ 220 ℃ for 0.5 ~ 2.0 minutes
  Ramp @ 2 ~ 4℃/Sec : Above 295℃ for 40~70 Sec (Peak : 360±10℃)
  Ramp Down @ 2 ~ 3.0 ℃ / Sec

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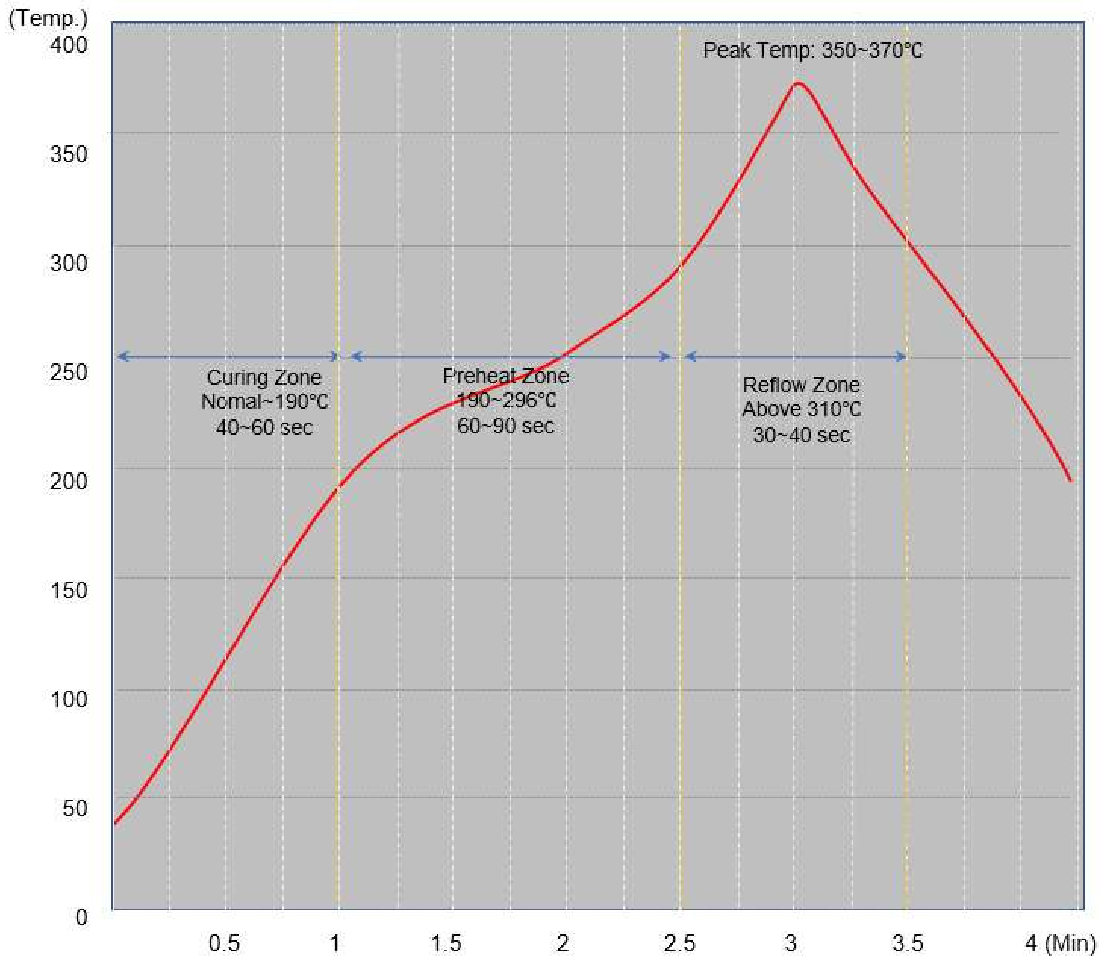
Standard Reflow Profile



Temperature Profile:
Ramp rate : <1.5℃/sec → Cure : Normal~190℃ for 40~60sec
Ramp rate : <0.6℃/sec → Preheat : 190~296℃ for 60~90sec
Ramp rate : <2.0℃/sec → Reflow : Above 310℃ for 30~40sec (Peak : 360±10℃)

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